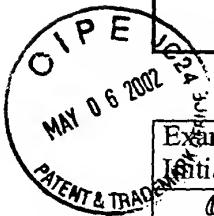


#5

Form 1449 (Modified)			Atty Docket No.	Application No.:
Information Disclosure Statement By Applicant			NSC1P131X1	10/080,913
(Use Several Sheets if Necessary)			Applicant: Nguyen et al.	
			Filing Date 2/21/02	Group 2823



U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
DR	A	6,130,473	10/10/00	Mostafazadeh et al.	257	666	04/02/98
	B						
	C						
	D						
	E						
	F						
	G						
	H						
	I						

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	J							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication		
DR	O	“Chip Scale Package: Design, Materials, Process, Reliability, and Applications”, John H. Lau and S. W. Ricky Lee, Chapter 1, Pages 1-41, (February 28, 1999) McGraw-Hill Professional Publishing; ISBN: 0070383049.		
DR	P	“Fundamentals of Microsystem Packaging”, Rao R. Tummala, Chapters 2, 10, and 17, (May 8, 2001) McGraw-Hill Professional Publishing; ISBN: 0071371699		
	Q			
Examiner		Date Considered 3/8/03		

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.